



Final Product/Process Change Notification

202203006F01

Issue Date: 25/03/2022
Effective Date: 30/06/2022

Here is your personalized quality information concerning products our customers and partners purchased from Ampleon.

For detailed information we invite you to [view this notification online](#)

Management Summary

Dies are optimized to improve the Idq drift behavior

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Optimized dies to improve Idq behaviour

Information Notification

To reduce the Idq drift over time the dies of the affected products have been optimized. This change has no impact on any RF or DC performance of the product.

Why do we implement this change?

To reduce the Idq drift of the affected product

Identification of affected Products

Product identification does not change

Product availability

Sample information

Samples are available upon request

Production

Planned first shipment

30/06/2022

Impact

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 2022-04-24.

Additional information

Affected products, sales history information as well as self qualification / additional documents can be accessed here: [view online](#)

Remarks